

# 820nm 2W Semiconductor Laser datasheet

P/N :WPFT-02A

## Features

808nm Central wavelength  
Output power 2W  
Multimode fiber



## Applications

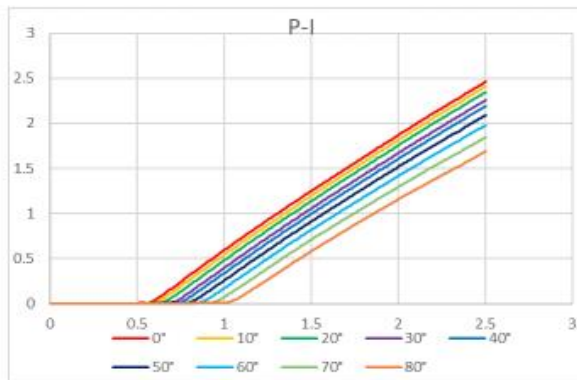
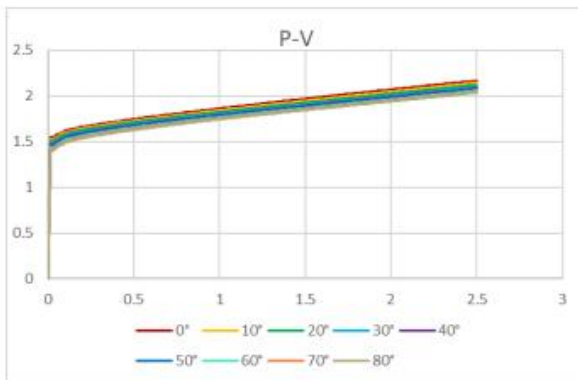
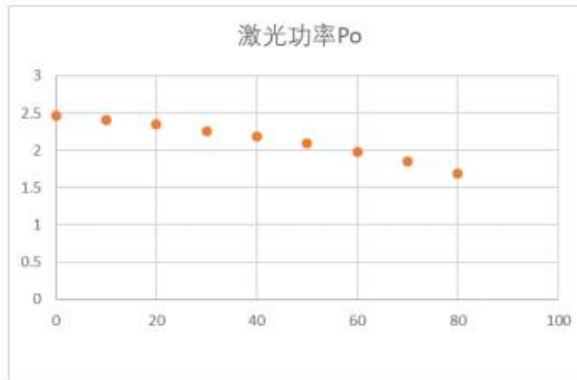
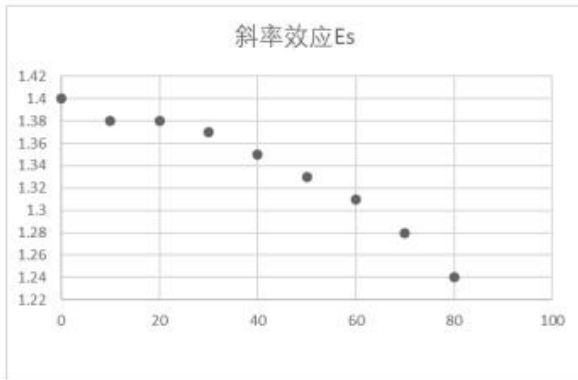
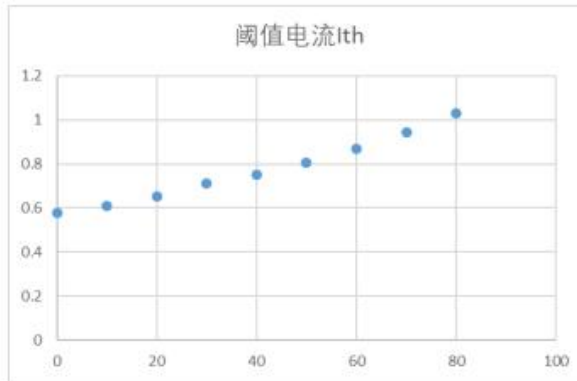
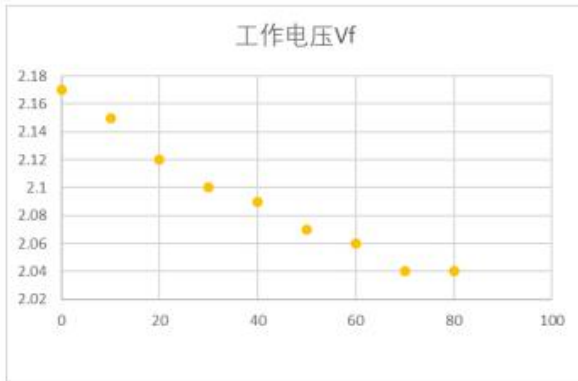
Sensing  
Communication equipment  
Scientific Research

## Specifications

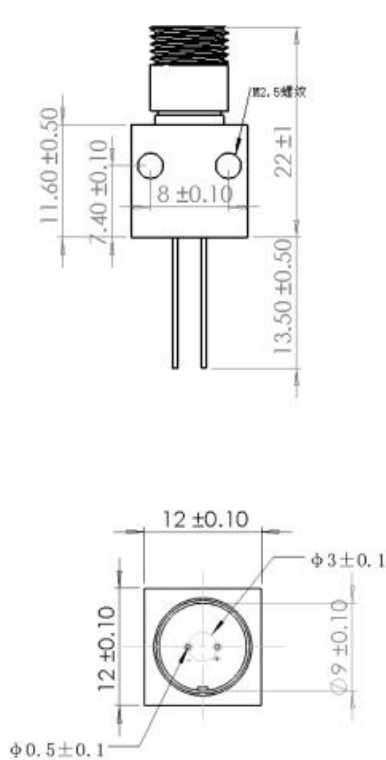
| Electrical/Optical Characteristics (T <sub>sub</sub> =25°C) |                               | Symbol                   | Units | Value  |       |     |
|---|-------------------------------|--------------------------|-------|--------|-------|-----|
|   |                               |                          |       | Min    | Typ.  | Max |
| Optical Parameters  | Output Power (CW)             | P <sub>0</sub>           | W     | 1.9    | 2     | -   |
|   | Center Wavelength             | $\lambda$                | nm    | 808±10 |       |     |
|   | Spectral Width (FWHM)         | $\Delta\lambda$          | nm    | -      | 3     | -   |
|   | Temperature Drift Coefficient | $\Delta\lambda/\Delta T$ | nm/°C | -      | 0.3   | -   |
| Electrical parameters                                       | Threshold current             | I <sub>th</sub>          | A     | -      | 0.65  | -   |
|   | Conversion Efficiency         | $\eta$                   | -     | -      | 35%   | -   |
|   | Operating Current             | I <sub>op</sub>          | A     | -      | 2.5   | -   |
|   | Operating Voltage             | V <sub>op</sub>          | V     | -      | 2.2   | -   |
| Fiber Optic Parameters                                      | Core Diameter                 | D <sub>core</sub>        | μm    | -      | 105   | -   |
|   | Cladding Diameter             | D <sub>clad</sub>        | μm    | -      | 125   | -   |
|   | Coating Diameter              | D <sub>buf</sub>         | μm    | -      | 250   | -   |
|   | Numerical Aperture            | N.A.                     | -     | -      | 0.22  | -   |
|   | Connector                     | -                        | -     | -      | FC    | -   |
| Other parameters  | Operating Temperature         | T <sub>op</sub>          | °C    | 10     | -     | 30  |
|   | Storage Temperature           | T <sub>at</sub>          | °C    | -20    | -     | 70  |
|   | Mean Time To Failure          | MTTF                     | h     | -      | 10000 | -   |
|   | Soldering Temperature         | T <sub>sold</sub>        | °C    | -      | -     | 260 |

|                |   |     |   |          |    |
|----------------|---|-----|---|----------|----|
| Soldering Time | t | sec | - | -        | 10 |
| Size           |   | mm  | - | 12*12*22 | -  |

### Temperature characteristic



## Outline Drawings(mm)



## Cautions

- 1.Avoid direct laser beam exposure to eyes and skin while the laser is operating.
- 2.Electrostatic discharge (ESD) protection measures must be taken during transportation, storage, and use. Short-circuit protection is required between pins during transportation and storage.
- 3.Use soldering method to connect leads, keeping solder joints as close to the pin roots as possible. Maintain soldering temperature below 260°C and duration less than 10 seconds.
- 4.Operate within rated current and voltage specifications.
- 5.Use constant current power supply and avoid surge currents during operation.
- 6.Ensure proper heat dissipation while the laser is operating, maintaining case temperature between 10°C and 30°C.

